

U.S. Department of Commerce, Patent and Trademark Office	Atty Docket No.	Application No.
SEP 22 2005	M-12524 US	10/056,154
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Applicant(s)	Confirmation No.
Substitute Form PTO 1449	Fortin, Vincent	2279
	Filing Date	Group
	23 January 2002	2823

U.S. Patent Documents

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA					
	AB					
	AC					
	AD					
	AE					
	AF					
	AG					
	AH					
	AI					
	AJ					
	AK					
	AL					

Foreign Patent Documents

							Translation	
	Document	Date	Country	Class	Subclass		Yes	No
	AM							
	AN							
	AO							
	AP							
	AQ							

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Le	AR	Hopwood, "Ionized physical vapor deposition of integrated circuit interconnects", <u>Physics of Plasmas</u> , May 1998, pp. 1624 - 1631
Le	AS	"Applied Materials Launches Advanced Cobalt Solution for Nano-Chip Manufacturing", Business Wire, Applied Materials, http://www.businesswire.com/cgi-bin/cnn-storydisplay.cgi?story=www/between/webboc/bw.1204...1 , Dec. 4, 2001, 1 page
	AT	

Examiner

Date Considered

11/8/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.